**Limitations and Deviations for CAL FM Test-Stand #6**

<table>
<thead>
<tr>
<th>Document #</th>
<th>Date effective</th>
</tr>
</thead>
<tbody>
<tr>
<td>LAT-TD-04317-01</td>
<td>16 August 04</td>
</tr>
</tbody>
</table>

**Author(s)**
- Gunther Haller

**Subsystem/Office**
- Electronics & DAQ Subsystem

Hard copies of this document are for REFERENCE ONLY and should not be considered the latest revision.
## CHANGE HISTORY LOG

<table>
<thead>
<tr>
<th>Revision</th>
<th>Effective Date</th>
<th>Description of Changes</th>
</tr>
</thead>
<tbody>
<tr>
<td>01</td>
<td>16 August 2004</td>
<td>Original</td>
</tr>
</tbody>
</table>
1. SCOPE ....................................................................................................................... ................................................................. 4
2. Environmental condition..................................................................................................... .......... 4
3. Differences to release drawings ............................................................................................. ....... 4
   3.1 Tower Power Supply......................................................................................................... .... 4
   3.2 Tower Electronics Module................................................................................................... .4
4. Changes from Test-Procedure................................................................................................. ...... 5
1. **SCOPE**

This document lists

- the environmental limitations and
- the differences of the test-stand shipped compared to the released test-stand drawings

2. **ENVIRONMENTAL CONDITION**

- The test-stand was only tested at room-temperature.

3. **DIFFERENCES TO RELEASE DRAWINGS**

3.1 **Tower Power Supply**

- LAT-DS-02389-01, PWB, complete
- LAT-DS-02390-04, Schematic: Sheet 1 - R1,R2,R11,R12 not loaded; Sheet 2, ZVR4 not loaded. Other sheets: Capacitors added across TRK Power Switch changed from 0.1microF to 1.0microF. Changed D500 to 1N4489. R532 = 402K.
- LAT-DS-02391-04, Material list, complete
- LAT-DS-00995-06, LAT-DS-00996-04, TPS enclosure: Entire unit is electroless nickel plated. No hard anodized was used.
- Added strip kapton tape below TEM to TPS connector
- Assembly number was not marked on chassis

3.2 **Tower Electronics Module**

- LAT-DS-01650-02 - Schematic Diagram, TEM CCA
- LAT-TD-02230-01 - Bill of Materials, TEM CCA
  - For resistors R648, R649, R650, R651 instead of single 50 Ohm value, two 100 Ohm resistors in parallel are used. They loaded with one soldered on top of second resistor.
Limitations and Deviations for CAL FM Test-stand #6

- LAT-DI-01646-04 - Circuit Card Assembly, TEM DAQ
- LAT-DI-01649-05 - Printed Wire Board, TEM
- LAT-DI-02583-01 - PWB Fab, Loading and Assembly
- LAT-DI-02588-02 - Connector and Cable Assembly, TEM CCA
- LAT-DI-00554-06 - TEM Box Base
  - Part is fully electroless nickel plated, no hard anodize was used
- LAT-DI-00555-06 - TEM Box Lid
  - Part is fully electroless nickel plated, no hard anodize was used
- LAT-DI-01481-04 - Assembly, Tower Electronics Module
  - Assy number not marked on chassis
- LAT-DI-01026-02 - TEM Connector Plate – countersink both sides equal
- LAT-DI-01031-02 - TEM Connector Pin
- LAT-TD-01880-01 - VHDL, LAT TEM GTIC FPGA
- LAT-TD-01881-01 - VHDL, LAT TEM GTIU FPGA
- LAT-DI-03582-01 - Spacer, TEM Connector – dimension 0.72 in overall length

FPGA version numbers:
- U45 – GTIC – version 1
- U62 – COMMCTL version 1 (Preprogrammed firmware version 9)

4. **CHANGES FROM TEST-PROCEDURE**

The test-procedure was in the process of official LAT-DOC release while the tests were performed. No changes to the procedure were done between the executing the tests and official release of the procedure.